

Title (en)

METHOD FOR THE SELECTIVE SURFACE TREATMENT OF NON-FLAT WORKPIECES

Title (de)

VERFAHREN ZUR SELEKTIVEN OBERFLÄCHENBEHANDLUNG VON NICHT PLATTENFÖRMIGEN WERKSTÜCKEN

Title (fr)

PROCÉDÉ DE TRAITEMENT DE SURFACE SÉLECTIF POUR PIÈCES NON PLATES

Publication

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Application

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Abstract (en)

[origin: WO2008128943A1] The invention relates to a method for the selective surface treatment of a first workpiece (1) on at least one of the metalized areas (3) of its upper (4) and/or underside (5), the first workpiece (1) being releasably joined to at least one additional workpiece (2) on one of its faces (4, 5) so as to be sealed from the exterior in at least one partial area and the selective surface treatment of the areas not covered by the joined section being carried out in a treatment phase. In order to make cooling and distribution of the metalized areas easier, the at least first workpiece (1) is not configured as a flat structure and is provided on at least one face with identically or differently metalized or non-metalized areas (3) or cavities or combinations thereof either across the whole surface or part of the surface and at least one additional metallic protective layer or an additional metallic coating is applied during the selective surface treatment.

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US 2002062987 A1 20020530 - UCHINONO YOSHIYUKI [JP], et al

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